

## Electronic Patent Application Fee Transmittal

Application Number:	10595303			
Filing Date:	19-May-2006			
Title of Invention:	Method and Device For Secure, Insulated and Electrically Conductive Assembling Of Treated Semiconductor Wafers			
First Named Inventor/Applicant Name:	Roy Knechtel			
Filer:	Jeff Vockrodt/Marcus Cunningham			
Attorney Docket Number:	60291.000048			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
Submission- Information Disclosure Stmt	1806	1	180	180
<b>Total in USD (\$)</b>				<b>180</b>